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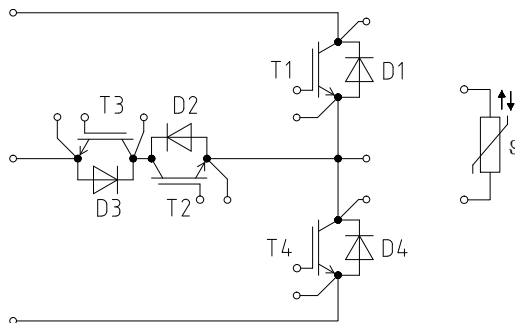
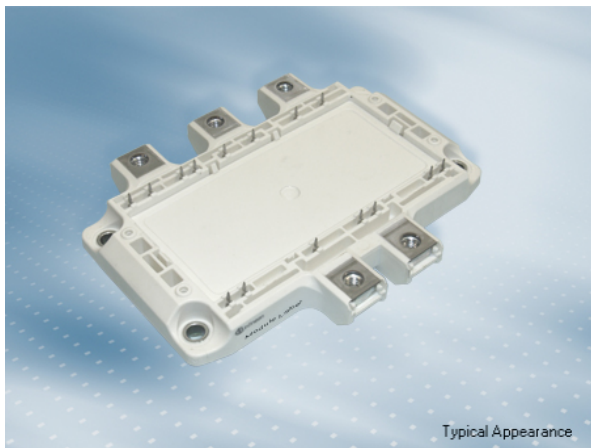
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EconoPACK™4 Modul mit aktiver "Neutral Point Clamp 2" Topologie und PressFIT / NTC  
EconoPACK™4 module with active "Neutral Point Clamp 2" topology and PressFIT / NTC

**Vorläufige Daten / Preliminary Data**



$V_{CES} = 1200V$   
 $I_{C\ nom} = 300A / I_{CRM} = 600A$

**Typische Anwendungen**

- Solar Anwendungen
- USV-Systeme

**Typical Applications**

- Solar Applications
- UPS Systems

**Elektrische Eigenschaften**

- Erweiterte Sperrschichttemperatur  $T_{vj\ op}$
- Niedrige Schaltverluste
- Niedriges  $V_{CEsat}$
- Trench IGBT 4
- $T_{vj\ op} = 150^{\circ}C$
- $V_{CEsat}$  mit positivem Temperaturkoeffizienten

**Electrical Features**

- Extended Operation Temperature  $T_{vj\ op}$
- Low Switching Losses
- Low  $V_{CEsat}$
- Trench IGBT 4
- $T_{vj\ op} = 150^{\circ}C$
- $V_{CEsat}$  with positive Temperature Coefficient

**Mechanische Eigenschaften**

- Isolierte Bodenplatte
- Kompaktes Design
- PressFIT Verbindungstechnik
- Standardgehäuse

**Mechanical Features**

- Isolated Base Plate
- Compact design
- PressFIT Contact Technology
- Standard Housing

**Module Label Code**

Barcode Code 128



DMX - Code



**Content of the Code**

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

prepared by: MK	date of publication: 2013-11-11	
approved by: MK	revision: 2.0	UL approved (E83335)



**Vorläufige Daten  
Preliminary Data**

**IGBT, T1 / T4 / IGBT, T1 / T4**

**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	1200	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_C = 100^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$ $T_C = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$I_{C\text{nom}}$ $I_C$	300 460	A A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	$I_{CRM}$	600	A
Gesamt-Verlustleistung Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$P_{\text{tot}}$	1650	W
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		$V_{GES}$	+/-20	V

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 300\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 300\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 300\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{sat}}$	1,75 2,05 2,10	2,15	V V V	
Gate-Schwellenspannung Gate threshold voltage	$I_C = 12,0\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{GEth}$	5,2	5,8	6,4	V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		$Q_G$	2,50			$\mu\text{C}$
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{Gint}$	2,5			$\Omega$
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{ies}$	18,5			nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{res}$	1,00			nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1200\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{CES}$			1,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{GES}$			100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{don}$	0,21 0,23 0,24			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_r$	0,09 0,10 0,11			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{doff}$	0,38 0,46 0,48			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Fallzeit, induktive Last Fall time, inductive load	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_f$	0,07 0,10 0,11			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 2300\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Gon} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{on}$	7,80 11,5 12,5			mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 2300\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Goff} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{off}$	13,0 19,0 20,5			mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 800\text{ V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$	$t_P \leq 10\ \mu\text{s}, T_{vj} = 25^{\circ}\text{C}$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	$I_{SC}$	1700 1400			A A
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		$R_{thJC}$			0,09	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{\text{Paste}} = 1\text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1\text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$			0,049	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{op}}$	-40		150	$^{\circ}\text{C}$

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**Vorläufige Daten  
Preliminary Data**

**Diode, D2 / D3 / Diode, D2 / D3**

**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	650	V
Dauergleichstrom Continuous DC forward current		$I_F$	300	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	$I_{FRM}$	600	A
Grenzlastintegral $I^2t$ - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	6700 6150	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 300\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 300\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 300\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_F$	1,45 1,35 1,30	1,85	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 300\text{ A}, -di_F/dt = 2300\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$I_{RM}$	120 190 200		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 300\text{ A}, -di_F/dt = 2300\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$Q_r$	9,70 29,0 34,0		$\mu\text{C}$ $\mu\text{C}$ $\mu\text{C}$
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 300\text{ A}, -di_F/dt = 2300\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{rec}$	2,40 6,20 7,00		mJ mJ mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode		$R_{thJC}$		0,22	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$	0,077		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

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**Vorläufige Daten  
Preliminary Data**

**IGBT, T2 / T3 / IGBT, T2 / T3**

**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	650	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_C = 52^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$ $T_C = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$I_{C\text{nom}}$ $I_C$	300 336	A A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	$I_{CRM}$	600	A
Gesamt-Verlustleistung Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$P_{\text{tot}}$	880	W
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		$V_{GES}$	+/-20	V

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 300\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 300\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 300\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{sat}}$	1,55 1,70 1,75	1,95	V V V	
Gate-Schwellenspannung Gate threshold voltage	$I_C = 4,80\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{GEth}$	4,9	5,8	6,5	V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		$Q_G$	3,20			$\mu\text{C}$
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{Gint}$	1,0			$\Omega$
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{ies}$	18,5			nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{res}$	0,57			nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{CES}$			1,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{GES}$			100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{don}$	0,08 0,10 0,10			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_r$	0,07 0,08 0,08			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{doff}$	0,35 0,38 0,39			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Fallzeit, induktive Last Fall time, inductive load	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_f$	0,09 0,12 0,12			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 3150\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Gon} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{on}$	4,50 6,80 7,95			mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 300\text{ A}, V_{CE} = 300\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 3350\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Goff} = 1,5\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{off}$	14,5 19,0 20,0			mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CE\text{max}} = V_{CES} - L_{SCE} \cdot di/dt$	$t_P \leq 10\ \mu\text{s}, T_{vj} = 25^{\circ}\text{C}$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	$I_{SC}$	1800 1400			A A
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		$R_{thJC}$			0,17	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{\text{Paste}} = 1\text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1\text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$			0,074	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{op}}$	-40		150	$^{\circ}\text{C}$

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**Vorläufige Daten  
Preliminary Data**

**Diode, D1 / D4 / Diode, D1 / D4**

**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	1200	V
Dauergleichstrom Continuous DC forward current		$I_F$	300	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	$I_{FRM}$	600	A
Grenzlastintegral $I^2t$ - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	15500 11500	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 300\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 300\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 300\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_F$	1,65 1,65 1,65	2,15	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 300\text{ A}, -di_F/dt = 3150\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$I_{RM}$	215 275 290		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 300\text{ A}, -di_F/dt = 3150\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$Q_r$	30,5 57,0 66,0		$\mu\text{C}$ $\mu\text{C}$ $\mu\text{C}$
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 300\text{ A}, -di_F/dt = 3150\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{rec}$	8,95 17,0 19,5		mJ mJ mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode		$R_{thJC}$		0,16	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K}) / \lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$	0,056		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj op}$	-40	150	$^{\circ}\text{C}$

**NTC-Widerstand / NTC-Thermistor**

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Nennwiderstand Rated resistance	$T_C = 25^{\circ}\text{C}$		$R_{25}$	5,00		$\text{k}\Omega$
Abweichung von R100 Deviation of R100	$T_C = 100^{\circ}\text{C}, R_{100} = 493\ \Omega$		$\Delta R/R$	-5	5	%
Verlustleistung Power dissipation	$T_C = 25^{\circ}\text{C}$		$P_{25}$		20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/50}$	3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/80}$	3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/100}$	3433		K

Angaben gemäß gültiger Application Note.  
Specification according to the valid application note.

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**Vorläufige Daten  
Preliminary Data**

**Modul / Module**

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V <sub>ISOL</sub>	2,5		kV
Material Modulgrundplatte Material of module baseplate			Cu		
Innere Isolation Internal isolation	Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al <sub>2</sub> O <sub>3</sub>		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		25,0 12,5		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		11,0 7,0		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 200		
			min.	typ.	max.
Modulstreuintuktivität Stray inductance module		L <sub>sCE</sub>		38	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T <sub>C</sub> = 25°C, pro Schalter / per switch	R <sub>CC'+EE'</sub>		0,75	mΩ
Lagertemperatur Storage temperature		T <sub>stg</sub>	-40		125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M5 - Montage gem. gültiger Applikationsschrift Screw M5 - Mounting according to valid application note	M	3,00	-	6,00 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	3,0	-	6,0 Nm
Gewicht Weight		G		400	g

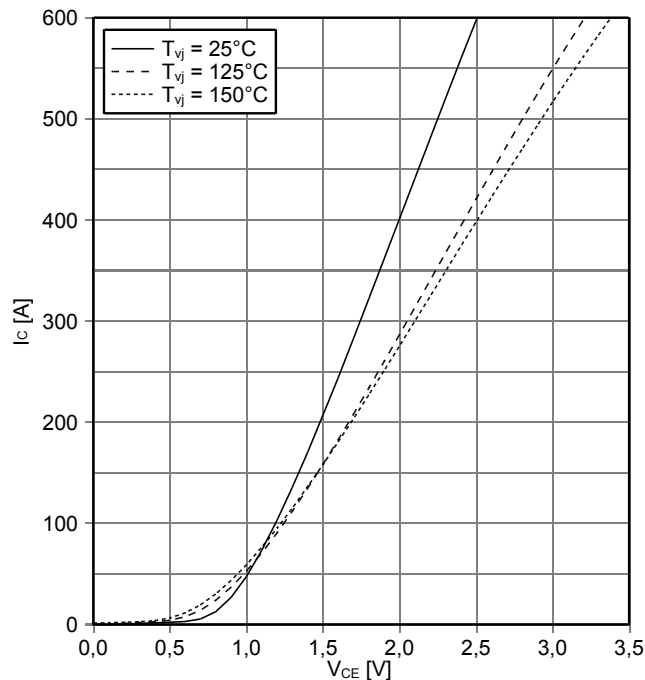
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**Vorläufige Daten**  
**Preliminary Data**

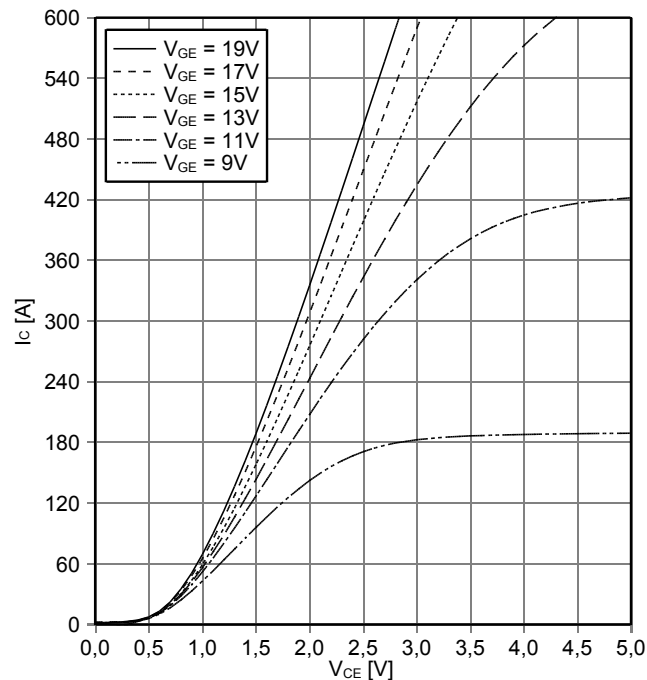
**Ausgangskennlinie IGBT, T1 / T4 (typisch)**  
**output characteristic IGBT, T1 / T4 (typical)**

$I_C = f(V_{CE})$   
 $V_{GE} = 15\text{ V}$



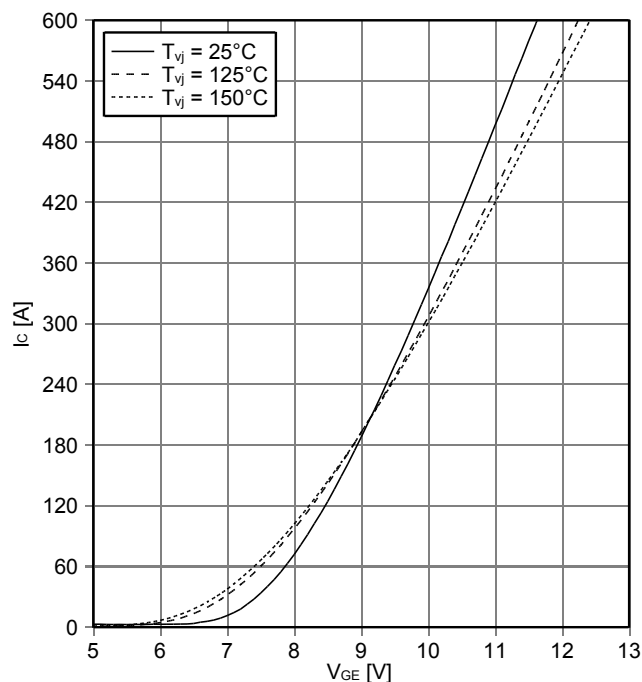
**Ausgangskennlinienfeld IGBT, T1 / T4 (typisch)**  
**output characteristic IGBT, T1 / T4 (typical)**

$I_C = f(V_{CE})$   
 $T_{vj} = 150^\circ\text{C}$



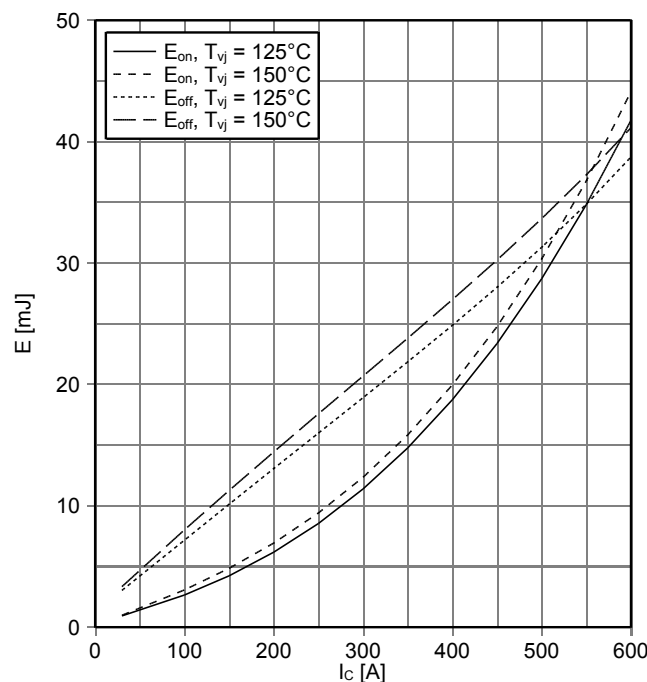
**Übertragungscharakteristik IGBT, T1 / T4 (typisch)**  
**transfer characteristic IGBT, T1 / T4 (typical)**

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



**Schaltverluste IGBT, T1 / T4 (typisch)**  
**switching losses IGBT, T1 / T4 (typical)**

$E_{on} = f(I_C), E_{off} = f(I_C)$   
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 1.5\ \Omega, R_{Goff} = 1.5\ \Omega, V_{CE} = 300\text{ V}$



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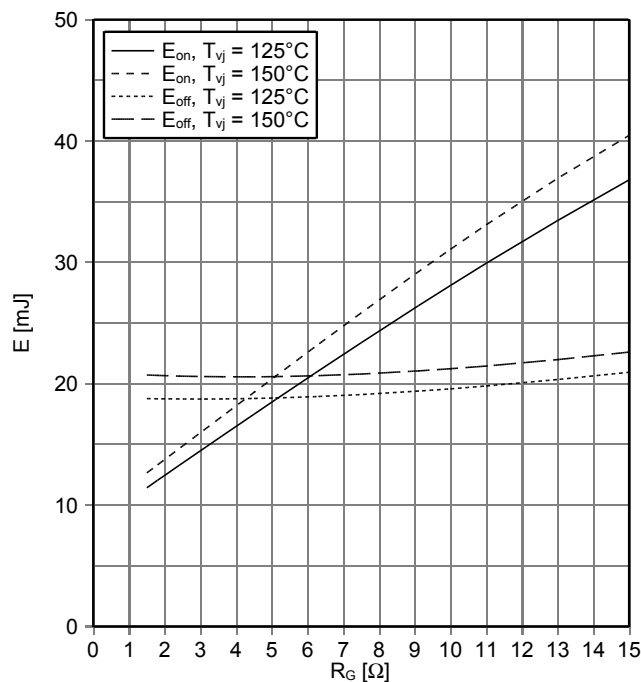




**Vorläufige Daten  
Preliminary Data**

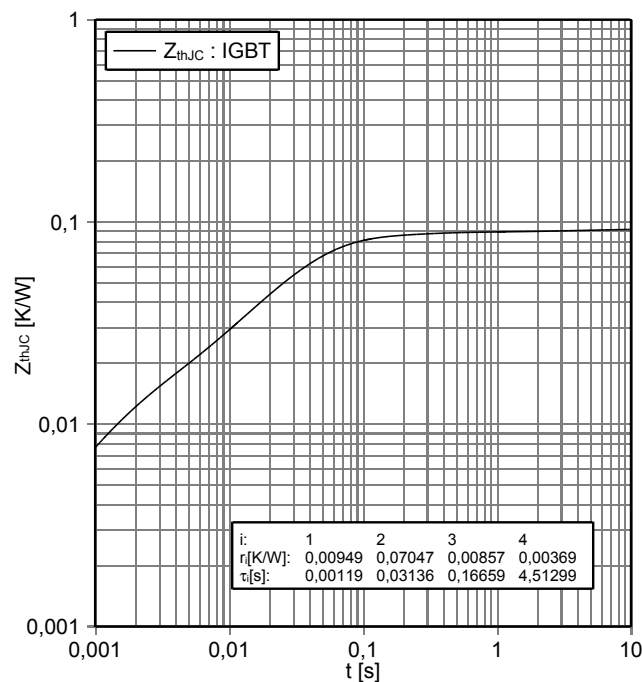
**Schaltverluste IGBT, T1 / T4 (typisch)  
switching losses IGBT, T1 / T4 (typical)**

$E_{on} = f(R_G), E_{off} = f(R_G)$   
 $V_{GE} = \pm 15\text{ V}, I_C = 300\text{ A}, V_{CE} = 300\text{ V}$



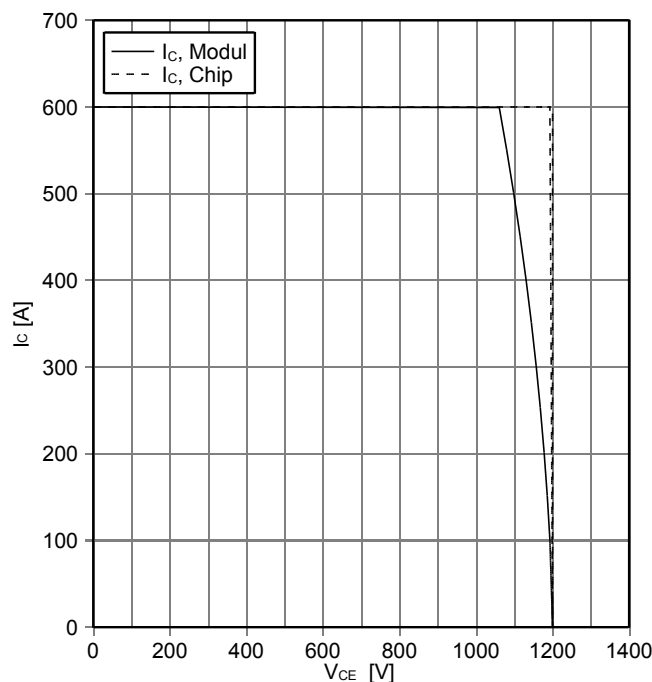
**Transienter Wärmewiderstand IGBT, T1 / T4  
transient thermal impedance IGBT, T1 / T4**

$Z_{thJC} = f(t)$



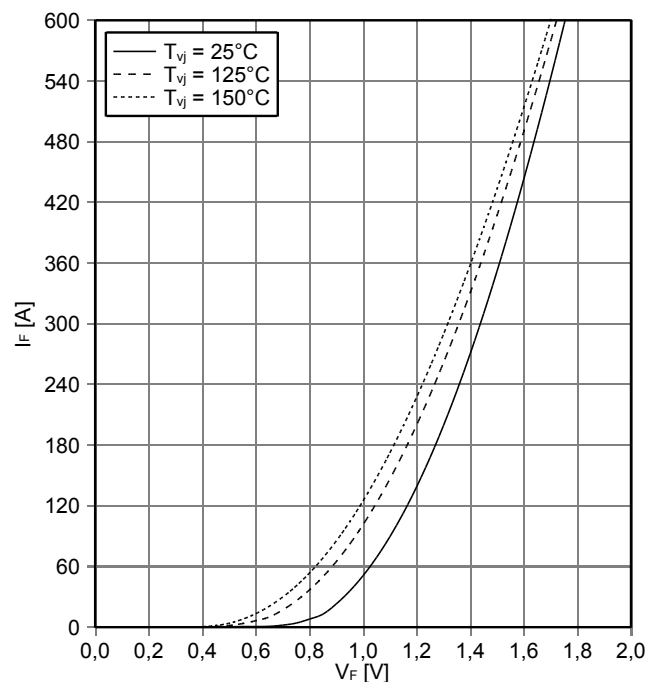
**Sicherer Rückwärts-Arbeitsbereich IGBT, T1 / T4 (RBSOA)  
reverse bias safe operating area IGBT, T1 / T4 (RBSOA)**

$I_C = f(V_{CE})$   
 $V_{GE} = \pm 15\text{ V}, R_{Goff} = 1.5\ \Omega, T_{vj} = 150^\circ\text{C}$



**Durchlasskennlinie der Diode, D2 / D3 (typisch)  
forward characteristic of Diode, D2 / D3 (typical)**

$I_F = f(V_F)$

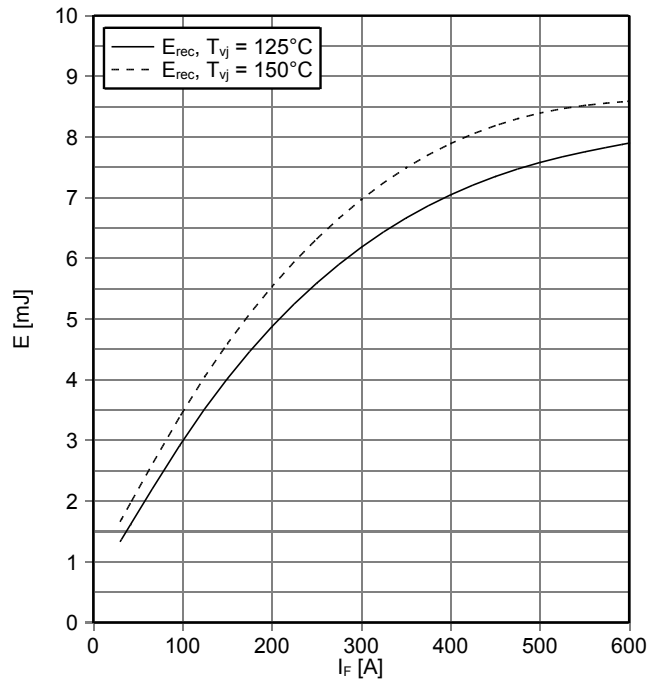


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**Vorläufige Daten**  
**Preliminary Data**

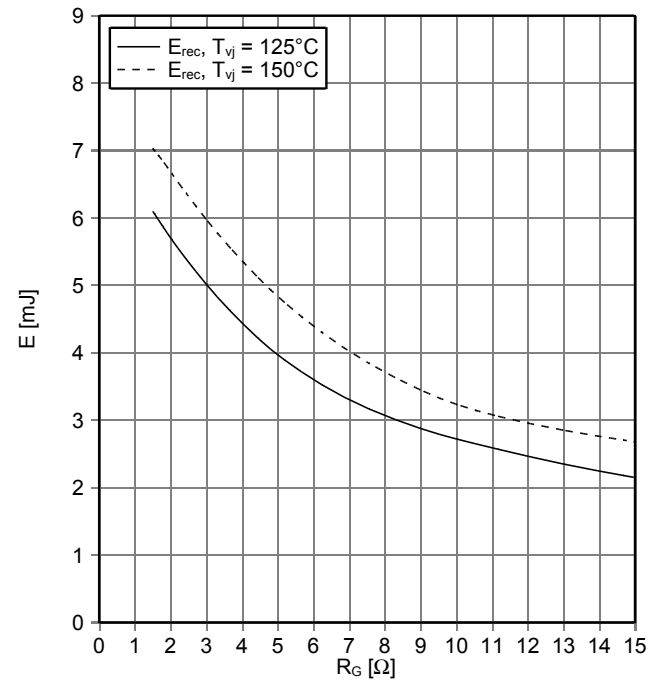
**Schaltverluste Diode, D2 / D3 (typisch)**  
**switching losses Diode, D2 / D3 (typical)**

$E_{rec} = f(I_F)$   
 $R_{Gon} = 1.5 \Omega, V_{CE} = 300 V$



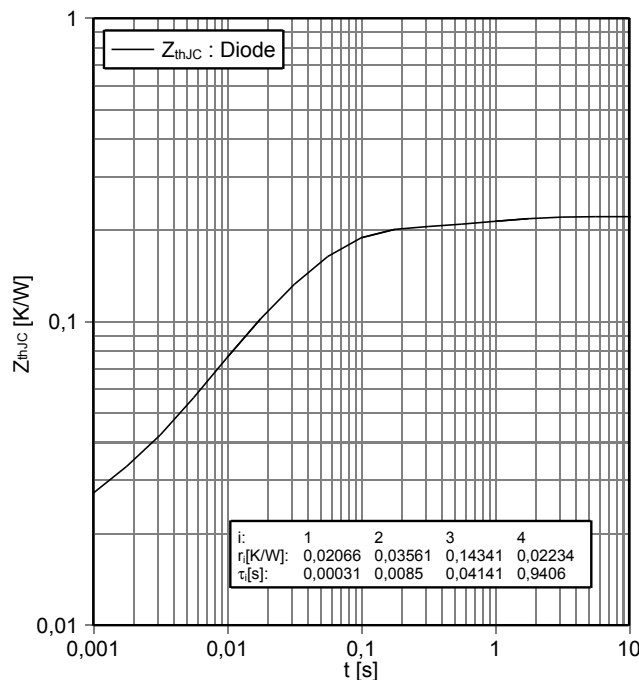
**Schaltverluste Diode, D2 / D3 (typisch)**  
**switching losses Diode, D2 / D3 (typical)**

$E_{rec} = f(R_G)$   
 $I_F = 300 A, V_{CE} = 300 V$



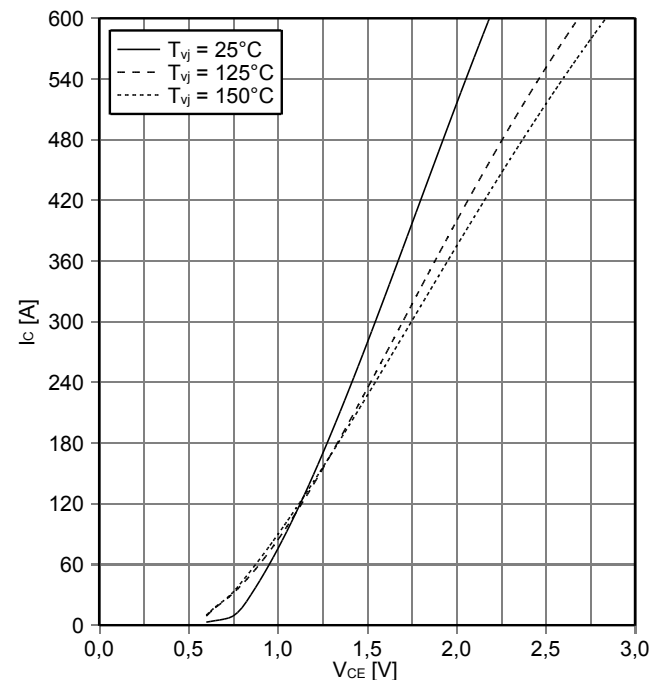
**Transienter Wärmewiderstand Diode, D2 / D3**  
**transient thermal impedance Diode, D2 / D3**

$Z_{thJC} = f(t)$



**Ausgangskennlinie IGBT, T2 / T3 (typisch)**  
**output characteristic IGBT, T2 / T3 (typical)**

$I_C = f(V_{CE})$   
 $V_{GE} = 15 V$



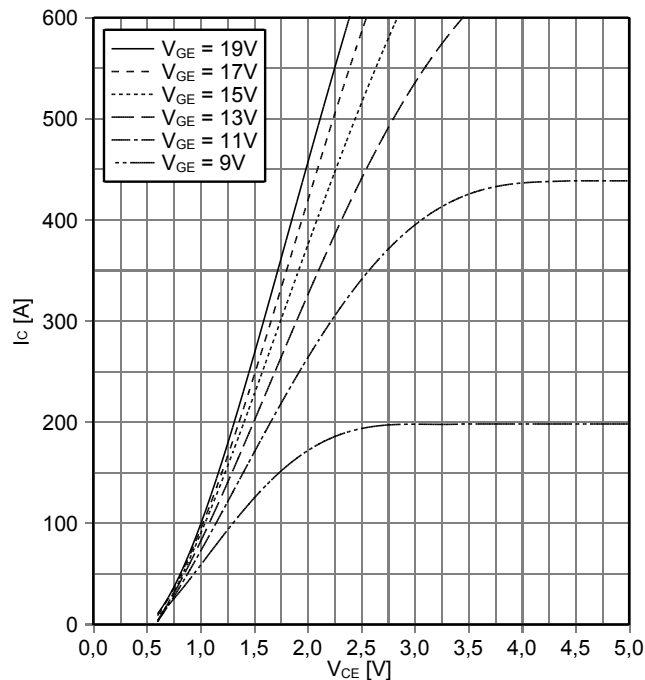
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**Vorläufige Daten**  
**Preliminary Data**

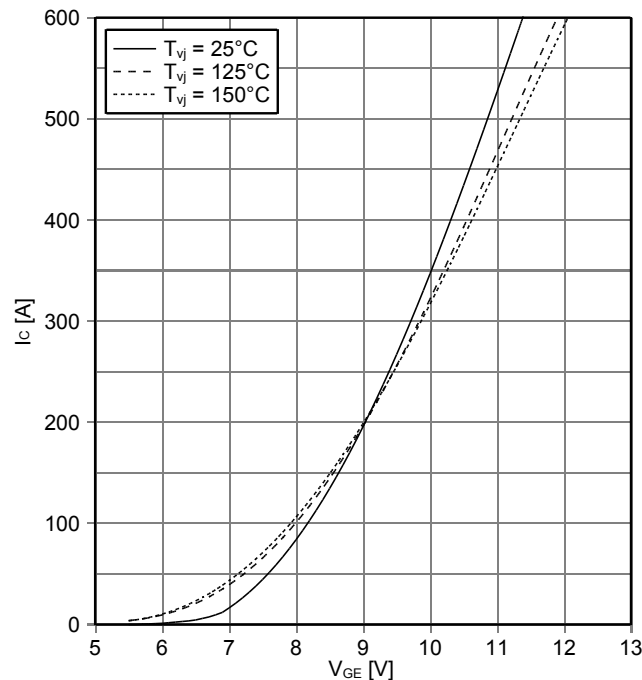
**Ausgangskennlinienfeld IGBT, T2 / T3 (typisch)**  
**output characteristic IGBT, T2 / T3 (typical)**

$I_C = f(V_{CE})$   
 $T_{vj} = 150^\circ\text{C}$



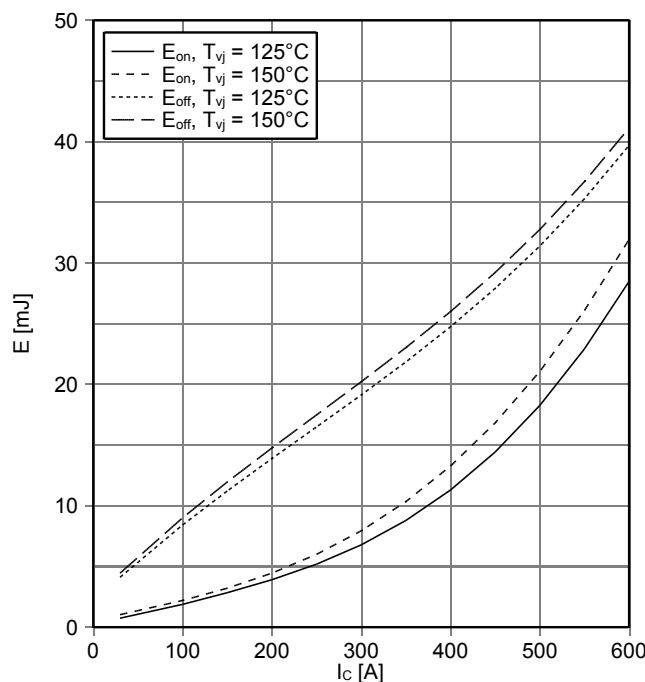
**Übertragungscharakteristik IGBT, T2 / T3 (typisch)**  
**transfer characteristic IGBT, T2 / T3 (typical)**

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



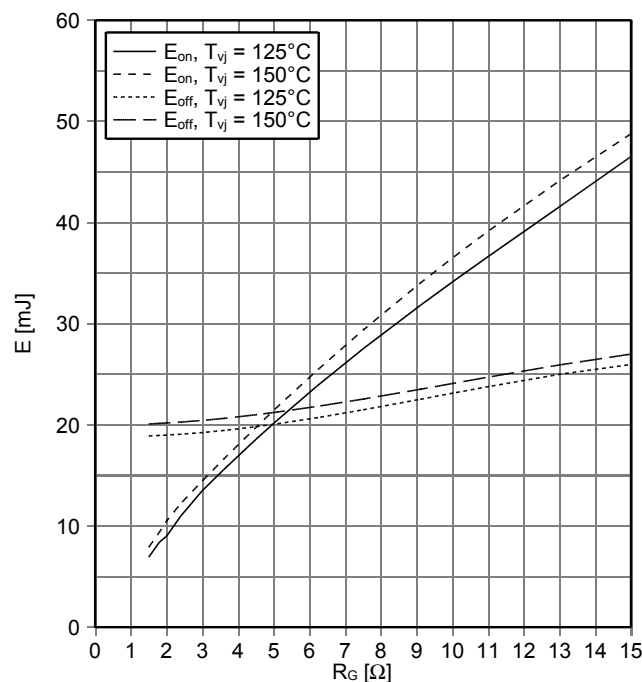
**Schaltverluste IGBT, T2 / T3 (typisch)**  
**switching losses IGBT, T2 / T3 (typical)**

$E_{on} = f(I_C), E_{off} = f(I_C)$   
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 1.5\ \Omega, R_{Goff} = 1.5\ \Omega, V_{CE} = 300\text{ V}$



**Schaltverluste IGBT, T2 / T3 (typisch)**  
**switching losses IGBT, T2 / T3 (typical)**

$E_{on} = f(R_G), E_{off} = f(R_G)$   
 $V_{GE} = \pm 15\text{ V}, I_C = 300\text{ A}, V_{CE} = 300\text{ V}$

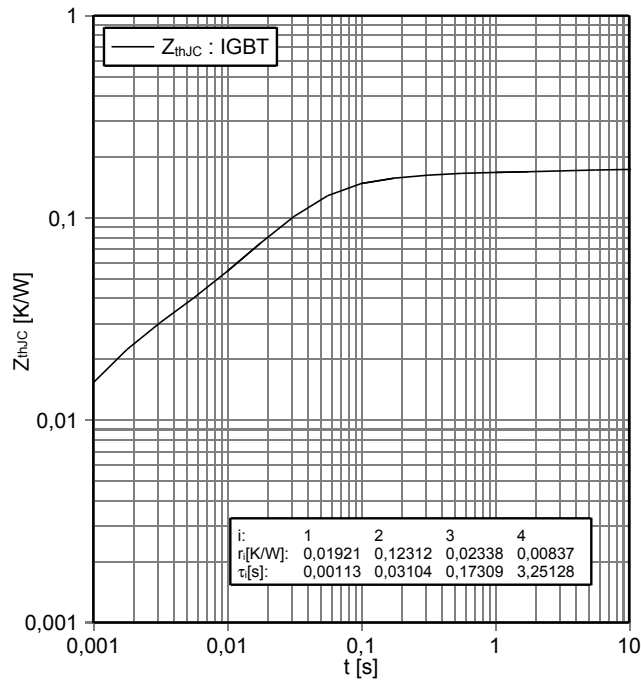


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**Vorläufige Daten  
Preliminary Data**

**Transienter Wärmewiderstand IGBT, T2 / T3  
transient thermal impedance IGBT, T2 / T3**

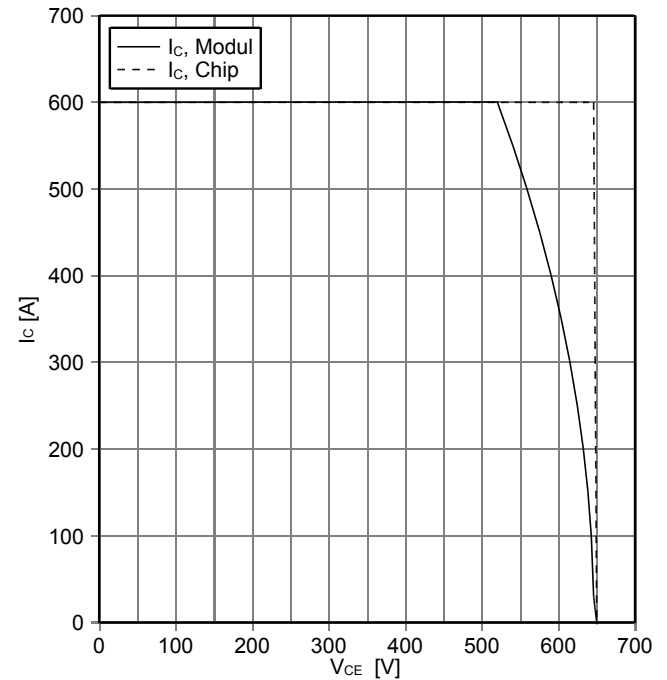
$Z_{thJC} = f(t)$



**Sicherer Rückwärts-Arbeitsbereich IGBT, T2 / T3 (RBSOA)  
reverse bias safe operating area IGBT, T2 / T3 (RBSOA)**

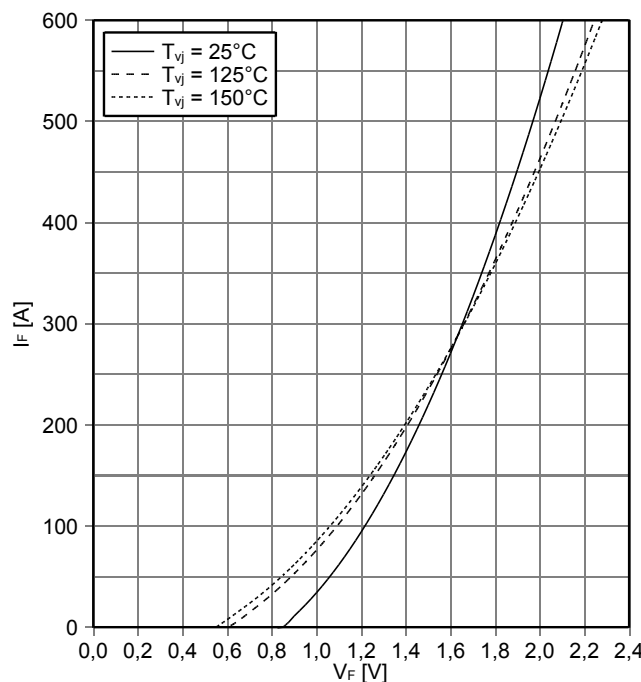
$I_C = f(V_{CE})$

$V_{GE} = \pm 15\text{ V}$ ,  $R_{Goff} = 1.5\ \Omega$ ,  $T_{vj} = 150^\circ\text{C}$



**Durchlasskennlinie der Diode, D1 / D4 (typisch)  
forward characteristic of Diode, D1 / D4 (typical)**

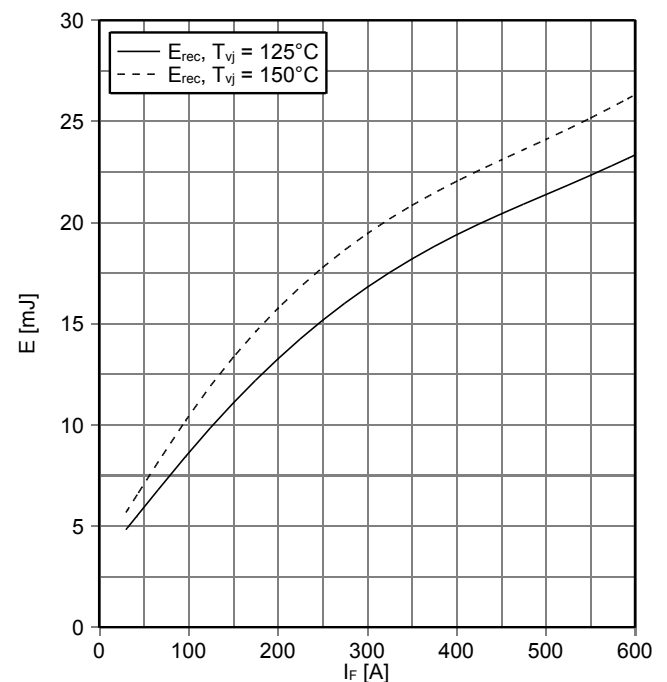
$I_F = f(V_F)$



**Schaltverluste Diode, D1 / D4 (typisch)  
switching losses Diode, D1 / D4 (typical)**

$E_{rec} = f(I_F)$

$R_{Gon} = 1.5\ \Omega$ ,  $V_{CE} = 300\text{ V}$

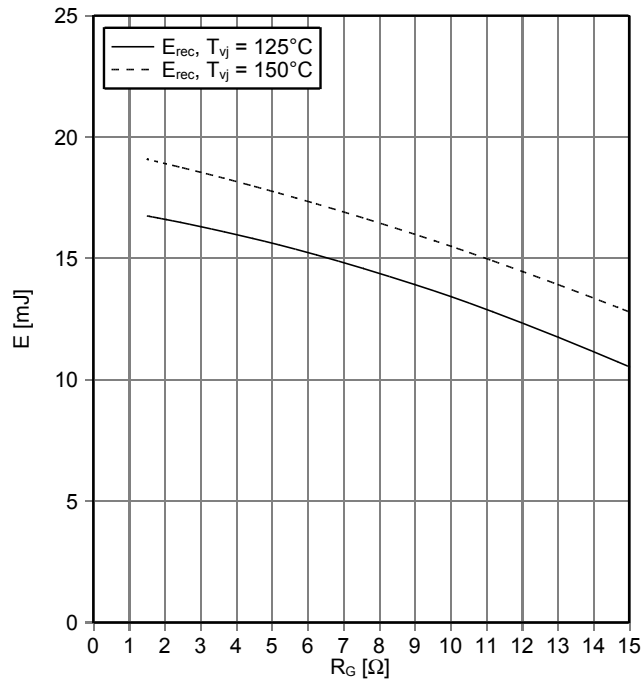


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**Vorläufige Daten  
Preliminary Data**

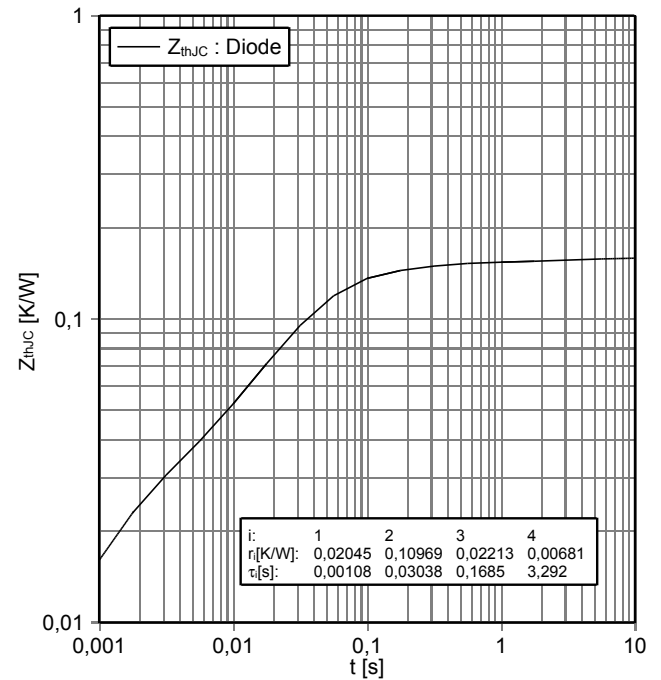
**Schaltverluste Diode, D1 / D4 (typisch)  
switching losses Diode, D1 / D4 (typical)**

$E_{rec} = f(R_G)$   
 $I_F = 300\text{ A}, V_{CE} = 300\text{ V}$



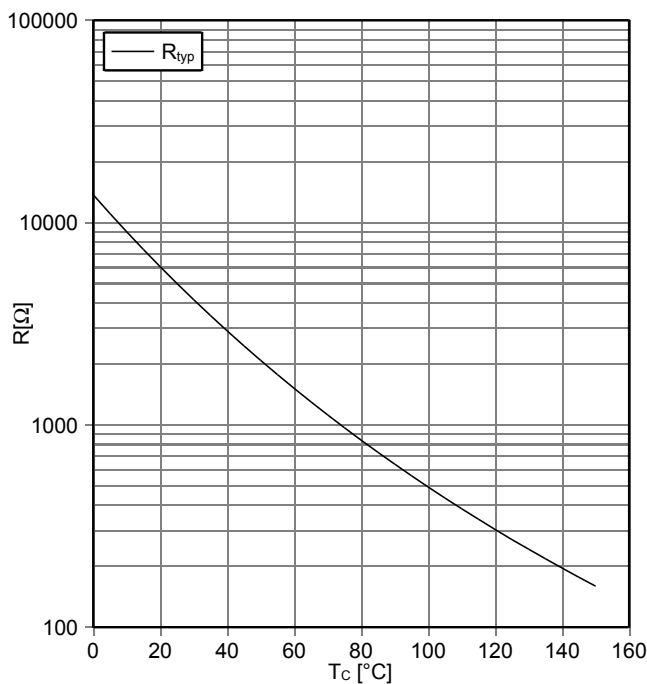
**Transienter Wärmewiderstand Diode, D1 / D4  
transient thermal impedance Diode, D1 / D4**

$Z_{thJC} = f(t)$



**NTC-Widerstand-Temperaturkennlinie (typisch)  
NTC-Thermistor-temperature characteristic (typical)**

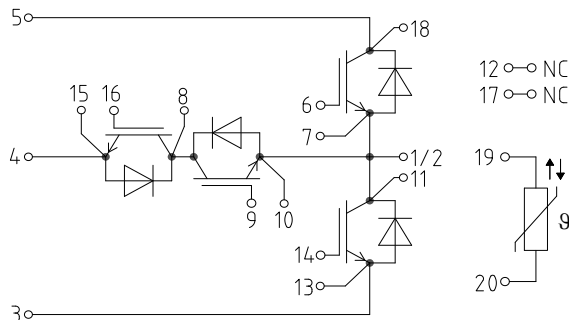
$R = f(T)$



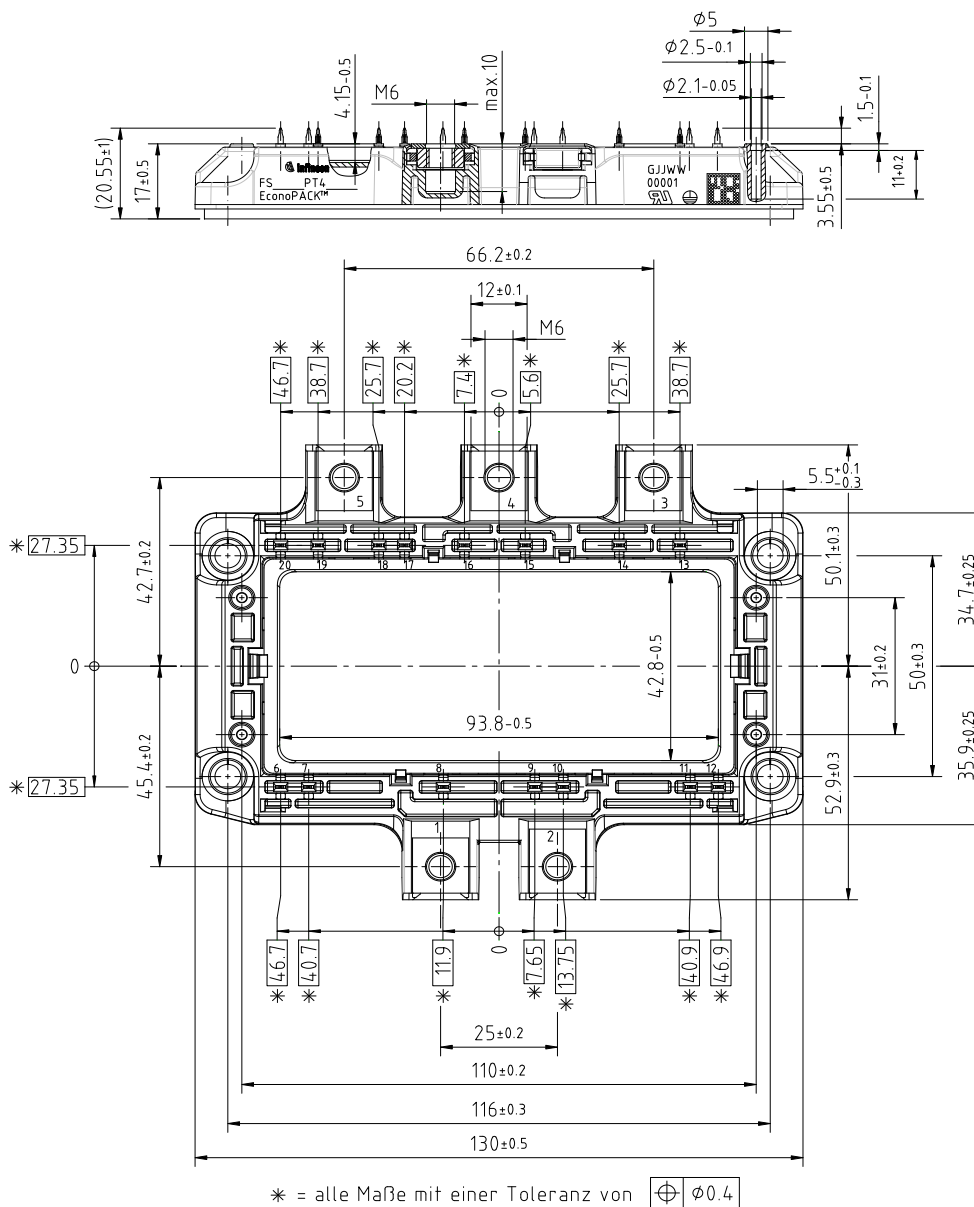
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Vorläufige Daten  
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Schaltplan / circuit\_diagram\_headline



Gehäuseabmessungen / package outlines



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**Vorläufige Daten  
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- the conclusion of Quality Agreements;
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